

SN74CBT16210C

20-BIT FET BUS SWITCH

5-V BUS SWITCH WITH –2-V UNDERSHOOT PROTECTION

SCDS115C – JANUARY 2003 – REVISED OCTOBER 2003

- Member of the Texas Instruments Widebus™ Family
- Undershoot Protection for Off-Isolation on A and B Ports Up To –2 V
- Bidirectional Data Flow, With Near-Zero Propagation Delay
- Low ON-State Resistance (r_{on}) Characteristics ($r_{on} = 3\ \Omega$ Typical)
- Low Input/Output Capacitance Minimizes Loading and Signal Distortion ($C_{iO(Off)} = 5.5\ \text{pF}$ Typical)
- Data and Control Inputs Provide Undershoot Clamp Diodes
- Low Power Consumption ($I_{CC} = 3\ \mu\text{A}$ Max)
- V_{CC} Operating Range From 4 V to 5.5 V
- Data I/Os Support 0 to 5-V Signaling Levels (0.8-V, 1.2-V, 1.5-V, 1.8-V, 2.5-V, 3.3-V, 5-V)
- Control Inputs Can Be Driven by TTL or 5-V/3.3-V CMOS Outputs
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Performance Tested Per JESD 22
 - 2000-V Human-Body Model (A114-B, Class II)
 - 1000-V Charged-Device Model (C101)
- Supports Both Digital and Analog Applications: PCI Interface, Memory Interleaving, Bus Isolation, Low-Distortion Signal Gating

DGG, DGV, OR DL PACKAGE
(TOP VIEW)

NC	1	48	1OE
1A1	2	47	2OE
1A2	3	46	1B1
1A3	4	45	1B2
1A4	5	44	1B3
1A5	6	43	1B4
1A6	7	42	1B5
GND	8	41	GND
1A7	9	40	1B6
1A8	10	39	1B7
1A9	11	38	1B8
1A10	12	37	1B9
2A1	13	36	1B10
2A2	14	35	2B1
V _{CC}	15	34	2B2
2A3	16	33	2B3
GND	17	32	GND
2A4	18	31	2B4
2A5	19	30	2B5
2A6	20	29	2B6
2A7	21	28	2B7
2A8	22	27	2B8
2A9	23	26	2B9
2A10	24	25	2B10

NC – No internal connection

description/ordering information

ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	SSOP – DL	Tube	SN74CBT16210CDL	CBT16210C
		Tape and reel	SN74CBT16210CDLR	
	TSSOP – DGG	Tube	SN74CBT16210CDGG	CBT16210C
		Tape and reel	SN74CBT16210CDGGR	
	TVSOP – DGV	Tape and reel	SN74CBT16210CDGVR	CY210C

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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description/ordering information (continued)

The SN74CBT16210C is a high-speed TTL-compatible FET bus switch with low ON-state resistance (r_{on}), allowing for minimal propagation delay. Active Undershoot-Protection Circuitry on the A and B ports of the SN74CBT16210C provides protection for undershoot up to -2 V by sensing an undershoot event and ensuring that the switch remains in the proper OFF state.

The SN74CBT16210C is organized as two 10-bit bus switches with separate output-enable ($1\overline{OE}$, $2\overline{OE}$) inputs. It can be used as two 10-bit bus switches or as one 20-bit bus switch. When $\overline{OE}$ is low, the associated 10-bit bus switch is ON, and the A port is connected to the B port, allowing bidirectional data flow between ports. When $\overline{OE}$ is high, the associated 10-bit bus switch is OFF, and the high-impedance state exists between the A and B ports.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} feature ensures that damaging current will not backflow through the device when it is powered down. The device has isolation during power off.

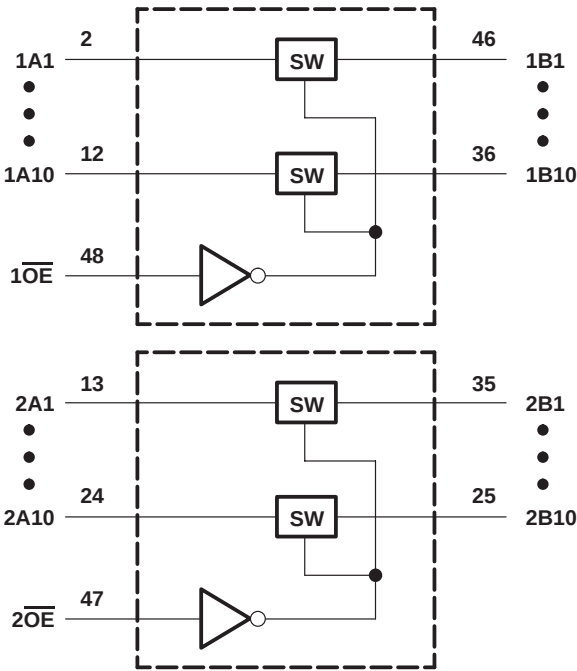
To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

FUNCTION TABLE

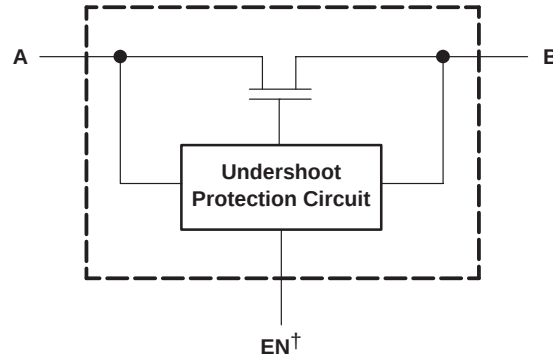
(each 10-bit bus switch)

INPUT $\overline{OE}$	INPUT/OUTPUT A	FUNCTION
L	B	A port = B port
H	Z	Disconnect

logic diagram (positive logic)



simplified schematic, each FET switch (SW)



† EN is the internal enable signal applied to the switch.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Control input voltage range, V_{IN} (see Notes 1 and 2)	–0.5 V to 7 V
Switch I/O voltage range, $V_{I/O}$ (see Notes 1, 2, and 3)	–0.5 V to 7 V
Control input clamp current, I_{IK} ($V_{IN} < 0$)	–50 mA
I/O port clamp current, $I_{I/OK}$ ($V_{I/O} < 0$)	–50 mA
ON-state switch current, $I_{I/O}$ (see Note 4)	±128 mA
Continuous current through V_{CC} or GND terminals	±100 mA
Package thermal impedance, θ_{JA} (see Note 5): DGG package	70°C/W
DGV package	58°C/W
DL package	63°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[‡] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. All voltages are with respect to ground unless otherwise specified.
 2. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 3. V_I and V_O are used to denote specific conditions for $V_{I/O}$.
 4. I_I and I_O are used to denote specific conditions for $I_{I/O}$.
 5. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 6)

	MIN	MAX	UNIT
V_{CC} Supply voltage	4	5.5	V
V_{IH} High-level control input voltage	2	5.5	V
V_{IL} Low-level control input voltage	0	0.8	V
$V_{I/O}$ Data input/output voltage	0	5.5	V
T_A Operating free-air temperature	–40	85	°C

NOTE 6: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V _{IK}	Control inputs	V _{CC} = 4.5 V,	I _{IN} = -18 mA			-1.8	V
V _{IKU}	Data inputs	V _{CC} = 5 V,	0 mA > I _I ≥ -50 mA, V _{IN} = V _{CC} or GND, Switch OFF			-2	V
I _{IN}	Control inputs	V _{CC} = 5.5 V,	V _{IN} = V _{CC} or GND			±1	μA
I _{OZ} [‡]		V _{CC} = 5.5 V,	V _O = 0 to 5.5 V, V _I = 0, Switch OFF, V _{IN} = V _{CC} or GND			±10	μA
I _{off}		V _{CC} = 0,	V _O = 0 to 5.5 V, V _I = 0			10	μA
I _{CC}		V _{CC} = 5.5 V,	I _{I/O} = 0, V _{IN} = V _{CC} or GND, Switch ON or OFF			3	μA
ΔI _{CC} [§]	Control inputs	V _{CC} = 5.5 V,	One input at 3.4 V, Other inputs at V _{CC} or GND			2.5	mA
C _{in}	Control inputs	V _{IN} = 3 V or 0			4.5		pF
C _{io} (OFF)		V _{I/O} = 3 V or 0, Switch OFF,	V _{IN} = V _{CC} or GND		5.5		pF
C _{io} (ON)		V _{I/O} = 3 V or 0, Switch ON,	V _{IN} = V _{CC} or GND		14.5		pF
r _{on} [¶]		V _{CC} = 4 V, TYP at V _{CC} = 4 V	V _I = 2.4 V, I _O = -15 mA		8	12	Ω
		V _{CC} = 4.5 V	V _I = 0, I _O = 64 mA		3	6	
			I _O = 30 mA		3	6	
			V _I = 2.4 V, I _O = -15 mA		5	10	

V_{IN} and I_{IN} refer to control inputs. V_I, V_O, I_I, and I_O refer to data pins.

[†] All typical values are at V_{CC} = 5 V (unless otherwise noted), T_A = 25°C.

[‡] For I/O ports, the parameter I_{OZ} includes the input leakage current.

[§] This is the increase in supply current for each input that is at the specified voltage level, rather than V_{CC} or GND.

[¶] Measured by the voltage drop between the A and B terminals at the indicated current through the switch. ON-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 4 V		V _{CC} = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
t _{pd} [#]	A or B	B or A		0.24		0.15	ns
t _{en}	$\overline{\text{OE}}$	A or B		6.5	1.5	6	ns
t _{dis}	$\overline{\text{OE}}$	A or B		6.5	1.5	6	ns

[#] The propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

undershoot characteristics (see Figures 1 and 2)

PARAMETER	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
V_{OUTU}	$V_{CC} = 5.5 \text{ V}$, Switch OFF, $V_{IN} = V_{CC}$ or GND	2	$V_{OH} - 0.3$		V

[†] All typical values are at $V_{CC} = 5 \text{ V}$ (unless otherwise noted), $T_A = 25^\circ\text{C}$.

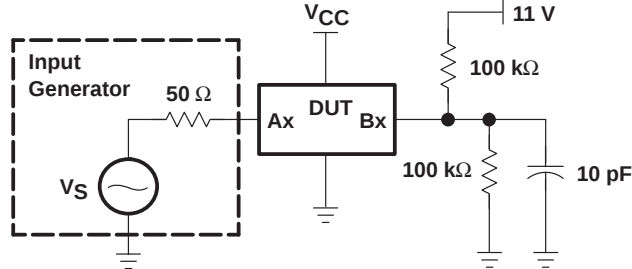


Figure 1. Device Test Setup

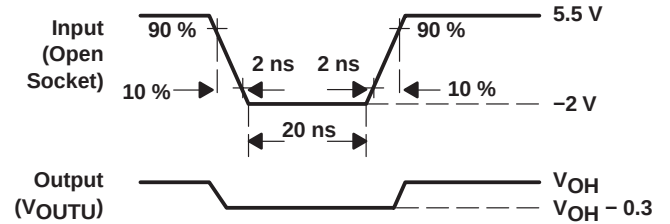


Figure 2. Transient Input Voltage (V_I) and Output Voltage (V_{OUTU}) Waveforms (Switch OFF)

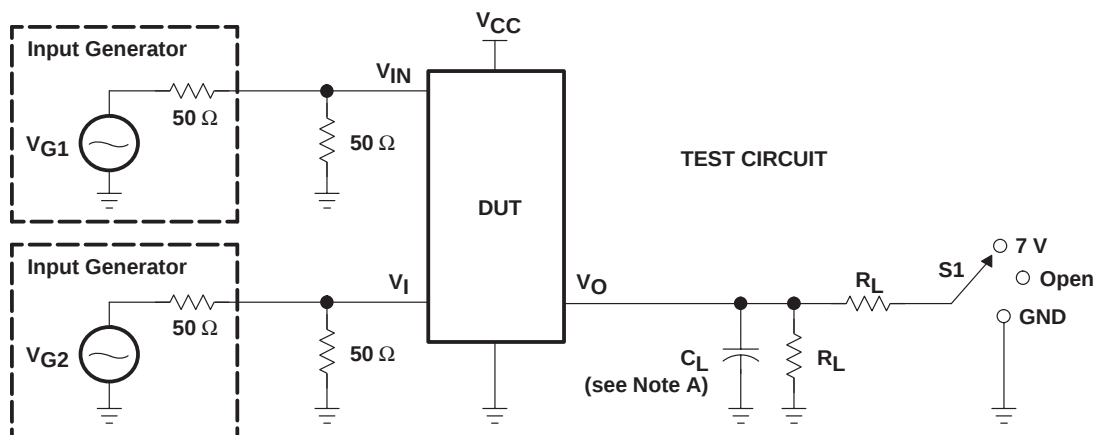
SN74CBT16210C

20-BIT FET BUS SWITCH

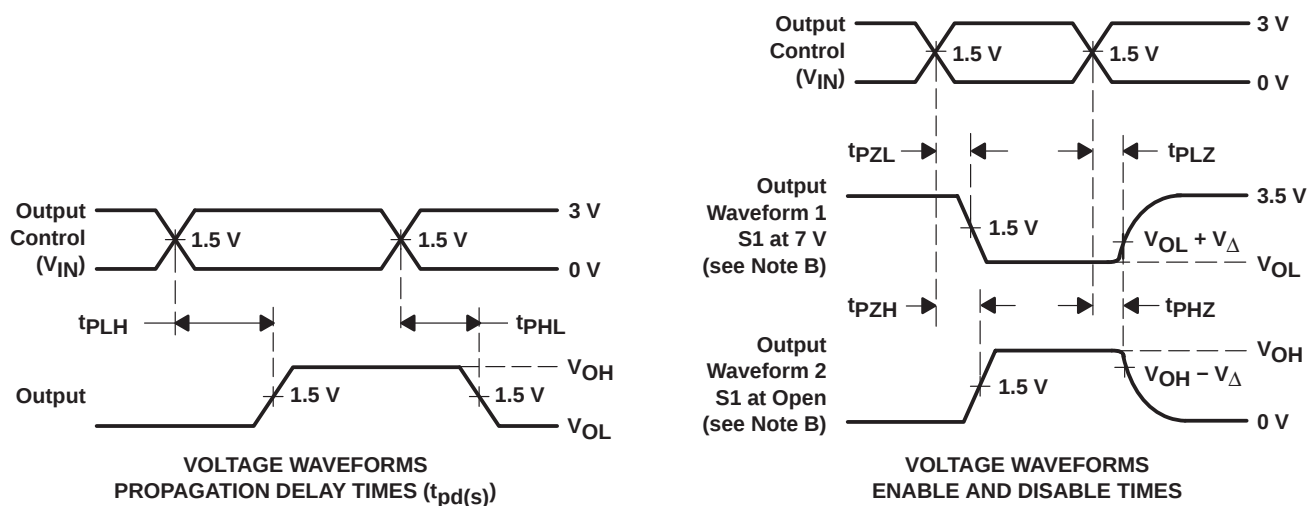
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PARAMETER MEASUREMENT INFORMATION



TEST	V_{CC}	$S1$	R_L	V_I	C_L	V_{Δ}
$t_{pd}(s)$	$5\text{ V} \pm 0.5\text{ V}$ 4 V	Open Open	500 Ω 500 Ω	V_{CC} or GND V_{CC} or GND	50 pF 50 pF	
t_{PLZ}/t_{PZL}	$5\text{ V} \pm 0.5\text{ V}$ 4 V	7 V 7 V	500 Ω 500 Ω	GND GND	50 pF 50 pF	0.3 V 0.3 V
t_{PHZ}/t_{PZH}	$5\text{ V} \pm 0.5\text{ V}$ 4 V	Open Open	500 Ω 500 Ω	V_{CC} V_{CC}	50 pF 50 pF	0.3 V 0.3 V



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\text{ }\Omega$, $t_r \leq 2.5\text{ ns}$, $t_f \leq 2.5\text{ ns}$.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as $t_{pd}(s)$. The t_{pd} propagation delay is the calculated RC time constant of the typical ON-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).
 - All parameters and waveforms are not applicable to all devices.

Figure 3. Test Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74CBT16210CDGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74CBT16210CDGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74CBT16210CDGVRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74CBT16210CDGVRG4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16210CDGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16210CDGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16210CDL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16210CDLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16210CDLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74CBT16210CDLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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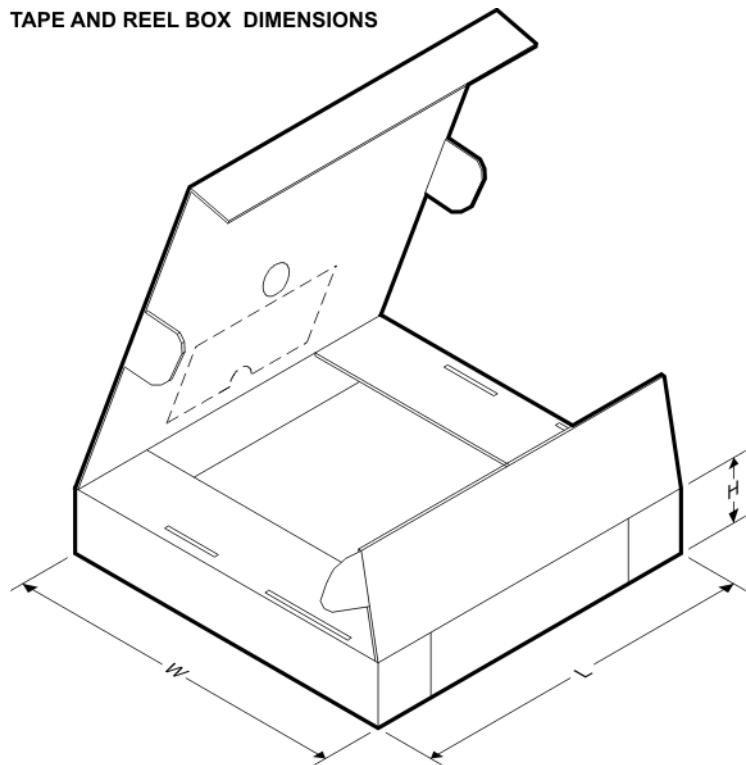
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74CBT16210CDGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	15.8	1.8	12.0	24.0	Q1
SN74CBT16210CDGVR	TVSOP	DGV	48	2000	330.0	24.4	6.8	10.1	1.6	12.0	24.0	Q1
SN74CBT16210CDLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74CBT16210CDGGR	TSSOP	DGG	48	2000	346.0	346.0	41.0
SN74CBT16210CDGVR	TVSOP	DGV	48	2000	346.0	346.0	41.0
SN74CBT16210CDLR	SSOP	DL	48	1000	346.0	346.0	49.0

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

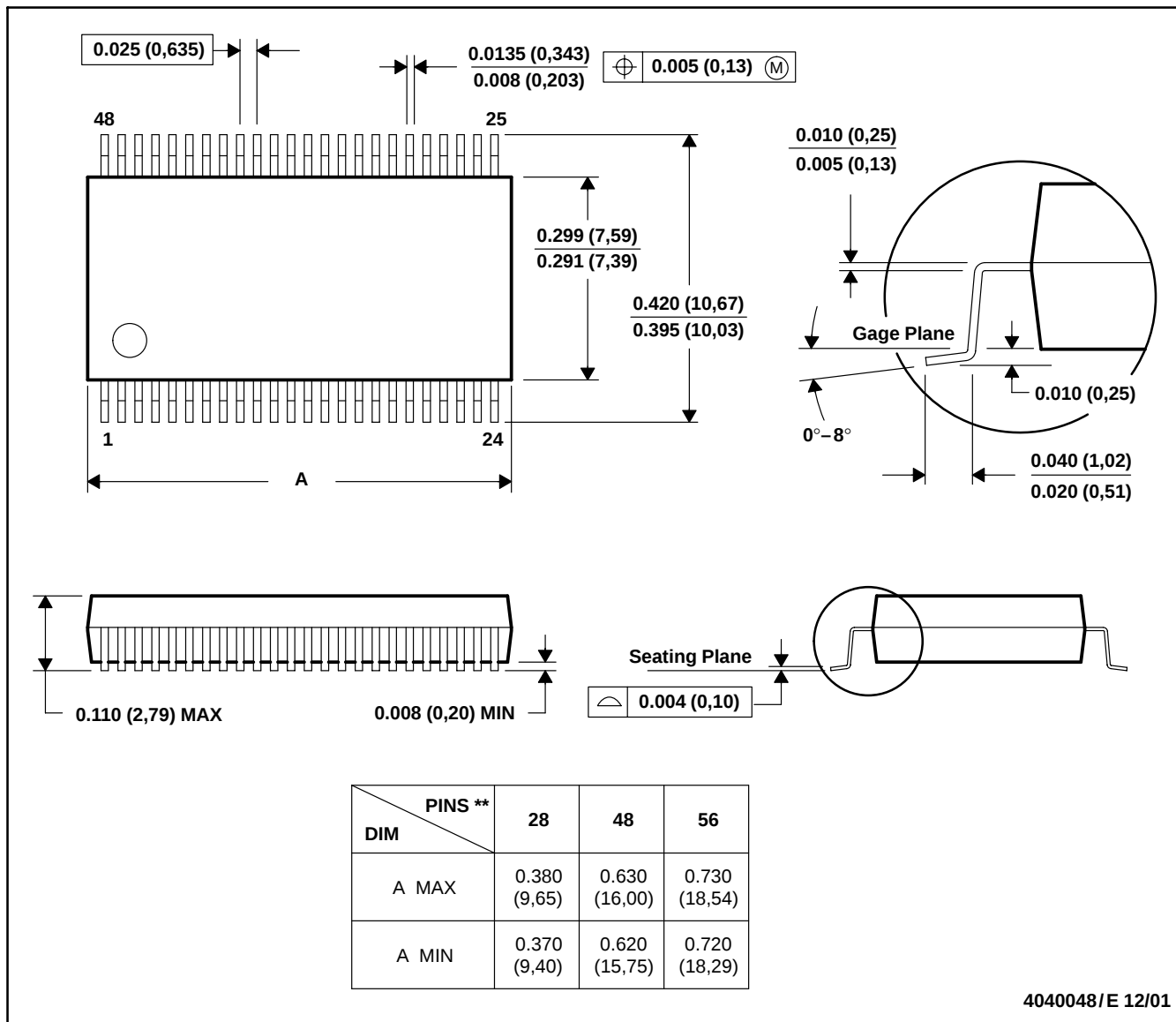


- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

DL (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MO-118

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

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